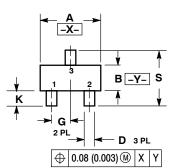
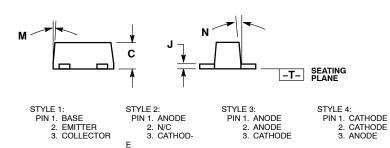
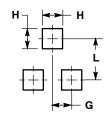


SC-89, 3 LEAD CASE 463C-03 ISSUE C

DATE 31 JUL 2003







RECOMMENDED PATTERN OF SOLDER PADS

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
- 4. 463C-01 OBSOLETE, NEW STANDARD 463C-02.

	MIL	LIMETE	ERS	INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.50	1.60	1.70	0.059	0.063	0.067
В	0.75	0.85	0.95	0.030	0.034	0.040
С	0.60	0.70	0.80	0.024	0.028	0.031
D	0.23	0.28	0.33	0.009	0.011	0.013
G	0.50 BSC			0.020 BSC		
Н	0.53 REF			0.021 REF		
J	0.10	0.15	0.20	0.004	0.006	0.008
K	0.30	0.40	0.50	0.012	0.016	0.020
L	1.10 REF			0.043 REF		
M			10			10
N			10 -			10 -
S	1.50	1.60	1.70	0.059	0.063	0.067

GENERIC MARKING DIAGRAM*



xx = Specific Device Code

= Date Code

*This information is generic. Please refer to device data sheet for actual part marking.

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